

# PBA-QM87

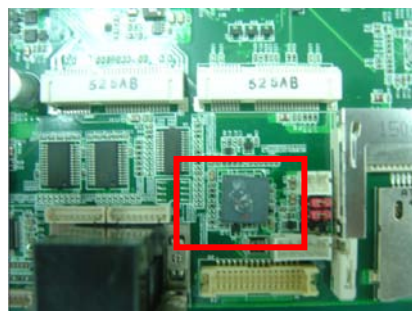
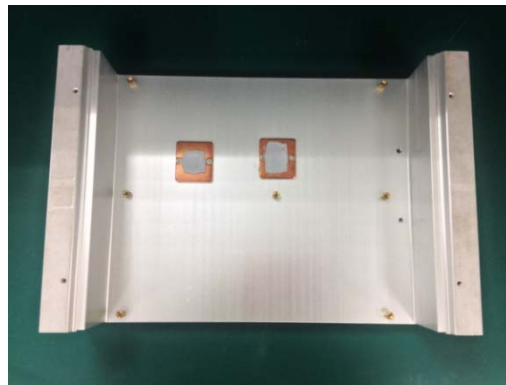
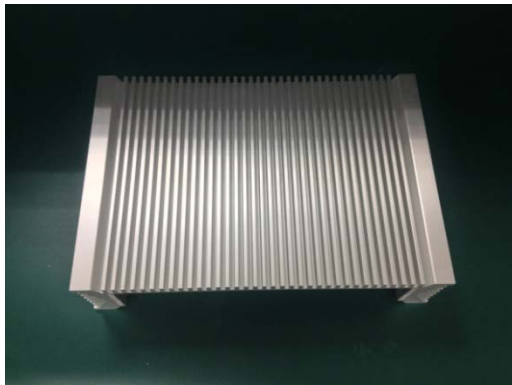
## Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>1. There are 5 component temperature was estimated to be in marginal temperature point in comparison with component datasheet.</u> <u>2. There are 1 component in the absence of Tc and Tj specification, So we are unable to determine.</u> <u>3. Thermal test occur “The 3D test was interrupted” error, when during run Burn in test 8.0.</u> <u>This 3D Graphics error (The 3D test was interrupted) is Intel knowing issue. Please reference the Intel release notes the Bug ID: 5557283 (Occur “The 3D test was interrupted” error when run Burnin 8.0 AC &amp; DC.)</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	6
Defect Unsolved	0	0	0	6

Issue date	Approval	Test Engineer
2015 / 06 / 17	KJ Wang	Juno Cheng

## Sample Configuration & Quantity Under Test

- **Model Name : PBA-QM87 A0.2**
- **M/B Name: PBA-QM87 A0.2**
- **BIOS : PBA-QM87 R0.2 (RM87AM02) (12/02/2014)**
- **CPU : Intel Core i5-4402E 1.60GHz**
- **Memory : Transcend DDR3L 1600 2GB / SEC K4B2G0846Q**
- **3.5" SATA HDD : Seagate ST380815AS 80GB**
- **Test Software : Windows 8 / Run PassMark Burn In Test 8.0 Pro**
- **Adapter : FSP / FSP084-DMAA1 12V 7A MAX**
- **AT Power : Zippy / HG2-6400P**
- **Heat sink:**



# Thermal Image Analysis

**1. Test Date: 2015-06-12**

**2. Test Product: PBA-QM87**

**3. Test Site: AAEON QE Dept.**

**4. Temperature Measurement:**

**4.1. 20 Channel Thermal Recorder:**

**4.1.1 SUNNICO Inc,**

**4.2.2 Model: ZR-RX45A**

**Date of Calibration: 2014/12/12**

**Serial Number: H30481978**

**4.2. IR Scanner: Infrared Camera**

**4.2.1 NEC Avio Infrared Technologies Co., Ltd.**

**4.2.2 Model: Thermo GEAR G100W2-D**

**Date of Calibration: 2014/12/19**

**Serial Number: 1051444**

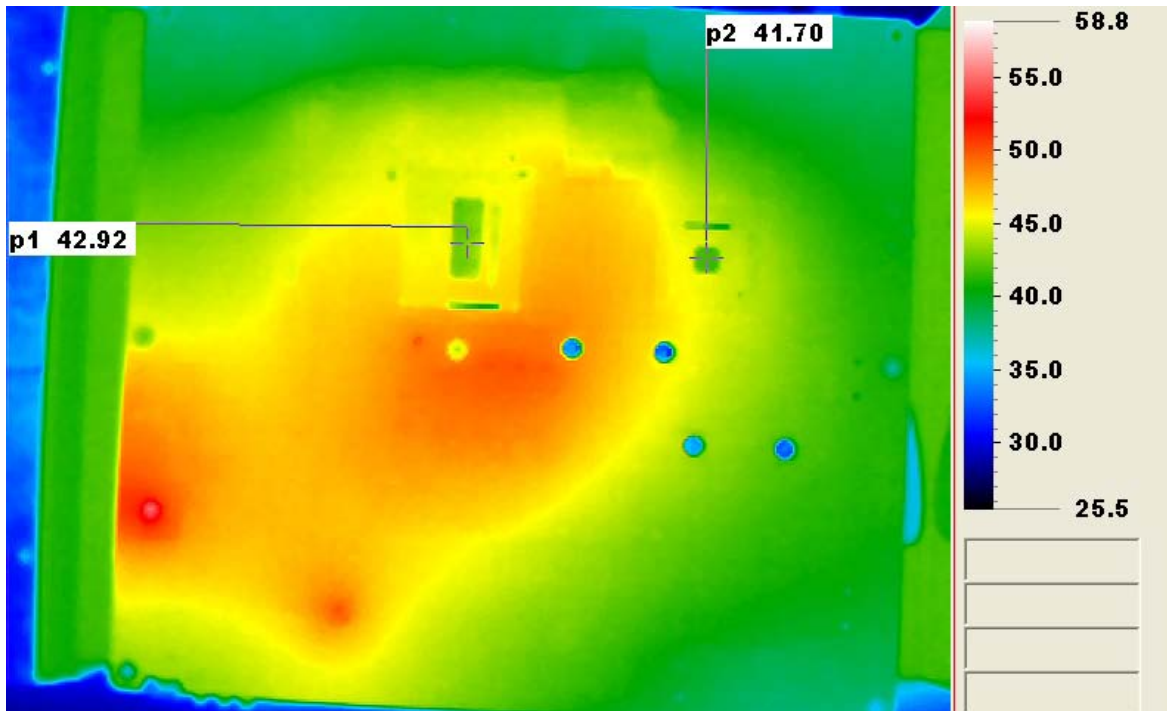
**5. Test Condition:**

**Test by DA-100: 25°C With Heat Sink**

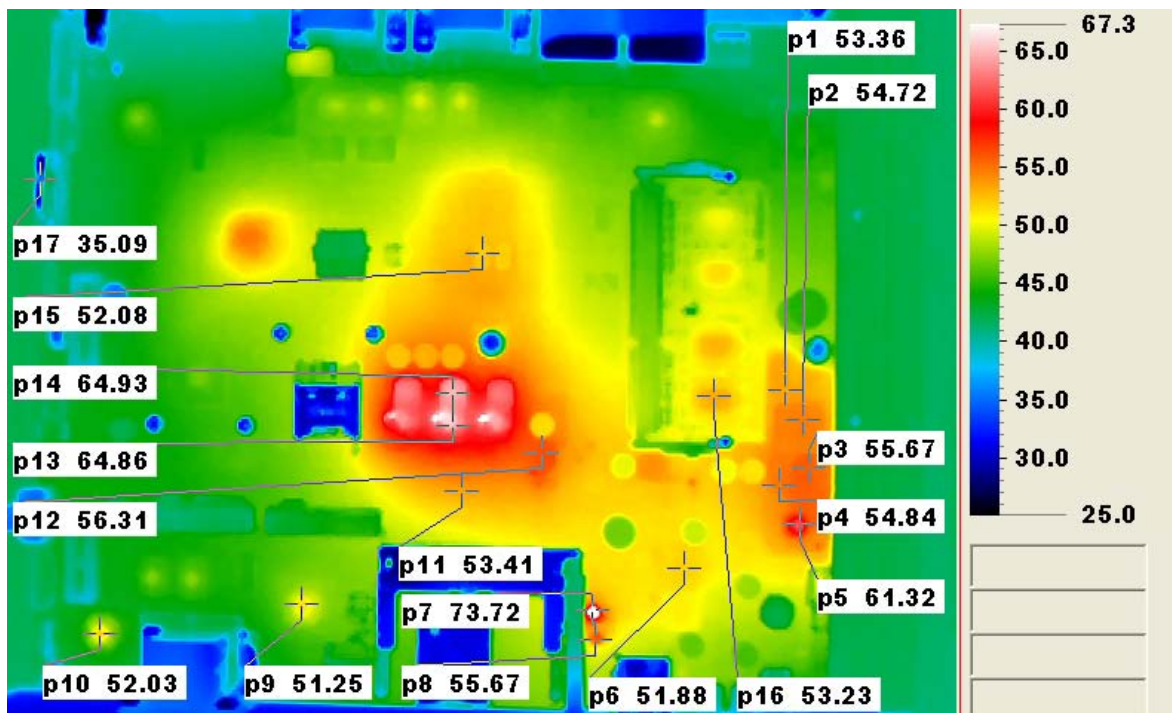
**6. Take Picture Time:**

**After power on 2 hours**

**Temperature Profile Test:**  
**Front Side:**

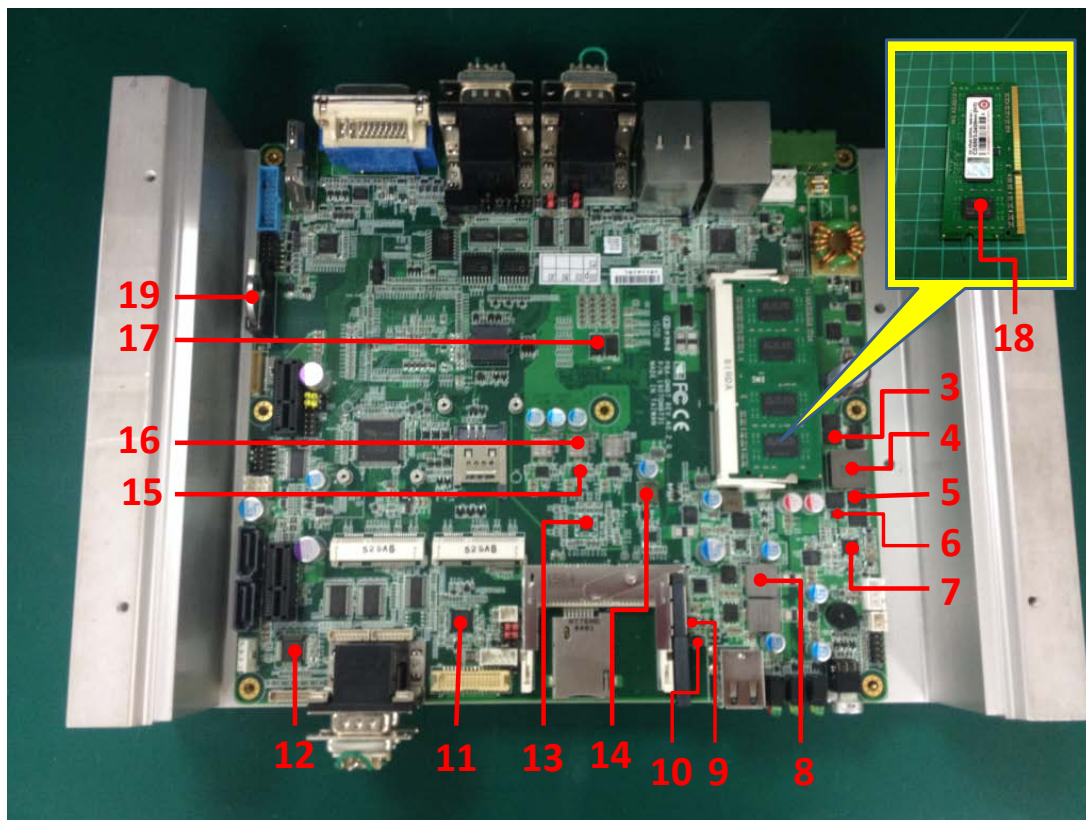
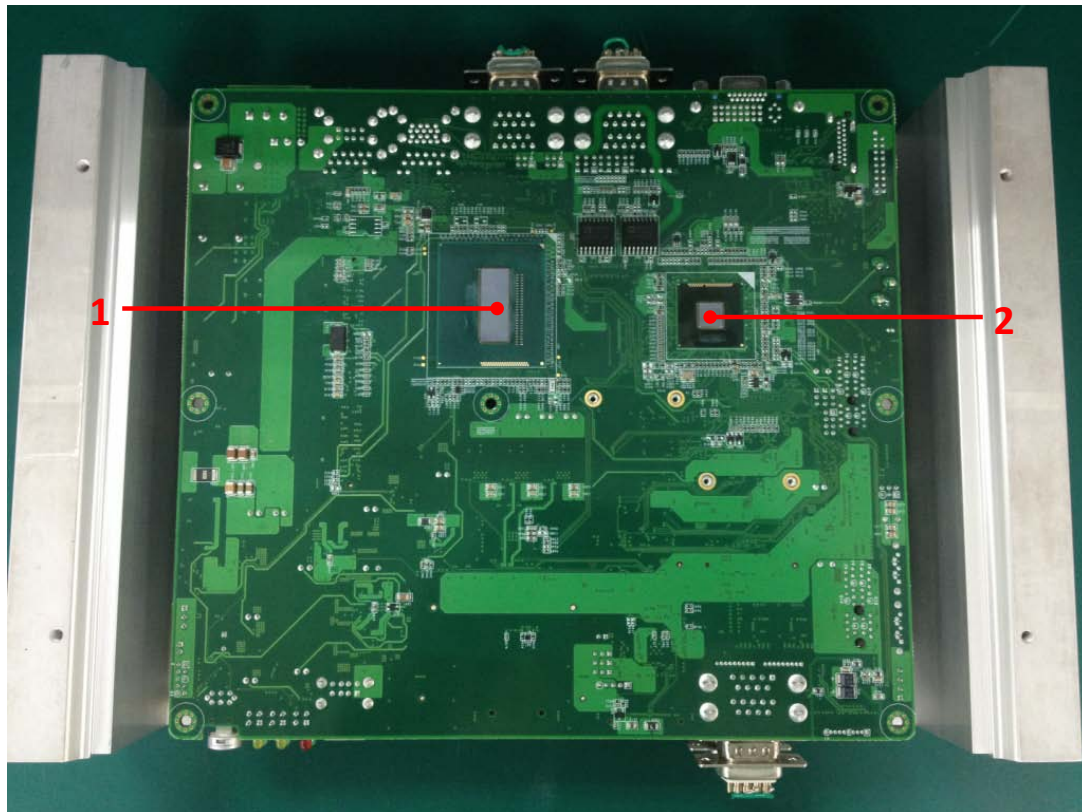


**Rear Side:**



### Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25°C	60°C	
1	U80	CPU - Intel Core i5-4402E 1.6GHz	100	53.1	88.1	
2	U79	IC.Chipset PCH.INTEL.DH82QM87 SR17C	108	52.1	87.1	
3	Q58	N-Channel.Vds=60V.20V.Ids=20A.FAIRCHILD.FDMS86540	125	56.4	91.4	
4	L6	COIL.2.2uH.DCR=4.6m ohm.GOTREND.GSTC135P-2R2MF	125	57.7	92.7	
5	U18	N-MOSFET.Ids=21.7A.SO-8FL.ON.NTMFS4C55NT1G	125	58.6	93.6	
6	D14	D Schottky.VDC=40V.Barrier Rectifiers.Willas.SK34A	100	58.5	93.5	Note3
7	U12	IC.QFN 32Pin.Regulator.LINEAR.LTC3780EUH#PBF	100	64.2	99.2	Note3
8	L2	COIL.1.5uH.DCR=3.8m ohm.GOTREND.GSTC104P-1R5MN	125	55.2	90.2	
9	U5	PWR.High-Side Switches with Flag.RICHTEK.RT9715AGBR	125	51.4	86.4	
10	TC1	CAP.150uF.6.3V.NEC-TOKIN.TEPSLB20J157M(35)8R	105	50	85	
11	U4	IC.Display Port to LVDS Converter.NXP.PTN3460BS	83.62	44.5	79.5	Note3
12	U2	IC.High Definition.Audio Codec.REALTEK.ALC892-CG	100.5	55.4	90.4	
13	U20	IC.D-CAP+TM.Step-Down Controller.TI.TPS51631ARSMR	100	58.4	93.4	Note3
14	L5	COIL.2.2uH.GOTREND.GSTD6030PE-2R2M	125	62.6	97.6	
15	U25	IC.Synchronous Buck NexFETTM.TI.CSD97374Q4M	125	71.7	106.7	
16	L8	COIL.0.24uH.DCR=1.2mohm.NEC/TOKIN.MPCH0730LR24	120	73.2	108.2	
17	C328	SP CAP.470uF.Panasonic.EEFSX0D471ER.A091046;1189647185	N/A	63.1	98.1	Note4
18	Memory	Transcend DDR3L 1600 2G (SEC / K4B2G0846Q)	95	60.3	95.3	Note3
19	BAT1	Maxell CR2032 H	85	36.1	71.1	
20	N/A	Air Temp.	N/A	25	60	

Note(\*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- Judgment Criteria:
  - Fail : Tm > Tc+5°C; The measured value is over specification plus margin.
  - Margin : Tc+5°C > Tm > Tc-10°C; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
  - Pass : Tm < Tc-10°C; The measured value is with safety margin.
- Defect NO. [P140908QED13](#)